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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Ritzdorf et al.
Application No. : 09/018,783 Confirmation No.: 1242
Filed : 2/4/98
For : METHOD AND APPARATUS FOR LOW TEMPERATURE
ANNEALING OF METALLIZATION MICRO-STRUCTURES
IN THE PRODUCTION OF A MICROELECTRONIC DEVICE

Examiner : Deven M. Collins
Art Unit : 2823
Docket No. : 29195.8162US
Date : October 1, 2001

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Washington, DC 20231

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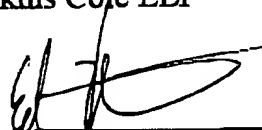
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Respectfully submitted,

Perkins Coie LLP



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Cited References (39)

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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**
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Sheet

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of

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*EXAMINER INITIALS	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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OTHER PRIOR ART-NON PATENT LITERATURE DOCUMENTS

*EXAMINER INITIALS	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume/issue number(s), publisher, city and/or country where published.
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Attorney Docket No.	29195.8162US

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Sheet	3	of	3	THOMPSON, C.V., and SMITH, H.I., "Secondary Grain Growth in Thin Films." <i>Material Research Society Symposium Proc.</i> , Vol. 57, Materials Research Society (1987).	
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EXAMINER				DATE CONSIDERED	
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